

Product/ Process Change Notification

Producti Process Change Nothication						
1.	PCN No.:		QPCN12023			
2.	Subject:		Bonding wire material change at SOD-123 (Switching & Zener) SMD Diode			
3.	То:		Refer to involved customer list			
4.	Issued by:		Owen Wang			
5.	Issue date:		3-Dec-2012			
6.	Proposed first ship date for change:		4-Mar-2013			
7.	Affected Product Identification					
Switching Diode & Array and Zener Diode & Array, SOD-123 package More details please see TSC involved P/N list.						
8. Change Description : (OLD Vs. NEW Comparison)						
	Old:		New:			
	➤ Gold bonding wire.		> Copper bonding wire.			
9.	Reason for Change:					
Follow the trend of common process in the market.						
10. Anticipated Impact: (form, fit, function, quality or reliability)						
	1. Product outline: No change					
		vire material change				
	•	No change				
	• •	No change				
		lo change lo change				
	` ,		ite code			
11	11. Qualification plan/result:					
 Comparison report see attached PPAP is available on demand 						
12. Sample availability Date:		3-Dec-2012				
13. Tentative implementation date:		3-Jan-2013				
14. Remarks						
15. Customer feedback required latest: (should we receive no feedback; the change will be deemed as accepted!)		3-Jan-2013				
16. Approved by:		Quayer Chen				



Product/ Process Change Notification Customer Approval Form_ QPCN12023

(Please tick the field what is valid for you!)							
	We agree with this proposed change and its schedule.						
	We have object	tions					
We need more information:							
	We need more	mormation.					
We need sample:							
Con	npany:						
Nan	ne:						
Add	Iress:						
Sigi	nature:		Date:				